Special Issue

Novel Technologies in Smart Manufacturing

Message from the Guest Editor

The integration of novel technologies into smart manufacturing systems is reshaping industrial production, enhancing flexibility, efficiency, and sustainability. This Special Issue aims to highlight the latest advances in intelligent systems, data-driven optimization, and emerging technologies that enable adaptive, connected, and autonomous manufacturing environments. Contributions that explore innovative applications of Al, IoT, robotics, digital twins, and additive manufacturing—across sectors such as automotive, aerospace, and electronics—are especially encouraged. This Issue welcomes both theoretical developments and practical implementations that advance the vision of smart manufacturing and beyond.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multidimensional network.

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